BROADCOM

PCN-CCX-001749

Product Change Notice

Issue Date: January 24, 2020

Change Type:

Add Assembly Production Site – ASE Taiwan

Parts Affected:

BCM53101MIMLG
BCM53101MIMLGG
BCM53101PIMLG
BCM53101EIMLG
BCM53101MKMLG
BCM53101PKMLG
BCM53101EKMLG

Description and Extent of Change:

Add ASE Taiwan as the assembly supplier for the above devices

Reasons for Change:

Current assembly factory (StatsChipPAC Singapore) is discontinuing the ASSEMBLY ARRAY and PLASTIC LEADED manufacturing operation

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There will be no change in fit, form, function, quality or reliability

Effective Date of Change:

May 31, 2020

BROADCOM

Qualification Data:

Package Qualification Reference#: 3655.0001, 3655.0002, 3655.0003
Fab Technology: 40nm
Package Type: DR-QFN
Package Size: 12x12mm
Lead Count: 148
Wire Bond Composition Cu_PD_Au
Mold Compound EME-G6321SB

Stress Test	Condition	Read points Cycles / Hrs.	Lot ID	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JESD22-A113E		Lot#1	130 units	0 failures	0 / 130
			Lot#2	130 units	0 failures	0 / 130
			Lot#3	130 units	0 failures	0 / 130
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	Lot#1	30 units	0 failures	0 / 30
			Lot#2	30 units	0 failures	0 / 30
			Lot#3	30 units	0 failures	0 / 30
uHast	130°C/85%RH JEDEC Std. 22-A102-C	192hrs	Lot#1	30 units	0 failures	0 / 30
			Lot#2	30 units	0 failures	0 / 30
			Lot#3	30 units	0 failures	0 / 30
HTSL	TA=150°C	1000hrs	Lot#1	30 units	0 failures	0 / 30
			Lot#2	30 units	0 failures	0 / 30
			Lot#3	30 units	0 failures	0 / 30

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.